### PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Takahiko IDO	12/28/2010
Yoshihiro KOGA	12/28/2010
Takumi ASANUMA	12/28/2010
Takashi ITO	12/28/2010

#### RECEIVING PARTY DATA

Name:	IBIDEN CO., LTD.	
Street Address:	1, Kandacho 2-Chome, Ogaki-Shi	
City:	Gifu	
State/Country:	JAPAN	
Postal Code:	503-8604	

### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13022544

### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: P5006US00

NAME OF SUBMITTER: Masayasu Mori

Total Attachments: 2

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PATENT REEL: 025756 FRAME: 0309

### Attorney Docket No.:

### **ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we the undersigned, \_(1) TAKAHIKO IDO. residing at Ibi-Gun. Gifu. Japan. (2) YOSHIHIRO KOGA. residing at Ibi-Gun. Gifu. Japan. (3) TAKUMI ASANUMA. residing at Ibi-Gun. Gifu. Japan and (4) TAKASHI ITO. residing at Ibi-Gun. Gifu. Japan, hereby sell, assign, and transfer to IBIDEN CO., LTD., a corporation of Japan having a principal place of business at \_1. Kandacho 2-Chome. Ogaki-Shi. Gifu 503-8604 Japan ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States patent, entitled:

HONEYCOMB STRUCTURE AND METHOD FOR MANUFACTURING HONEYCOMB STRUCTURE	
<ul><li>     ⊠ which has been executed by the undersigned concurrently herewith,</li><li>     □ which was filed on and assigned Serial No</li></ul>	

and in to said application and all divisional, continuing, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all assignments and powers of attorney; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

# Each Inventor: Please Sign and Date Below:

December 28		Takahiko Ado	
Date		Name: TAKAHIKO IDO	
December 28	, 2010_	Yoshihiro koga.	
Date		Name: YOSHIHIRO KOGA	
December 28	, 20 <sup>10</sup>	Takumi Asanuma	
Date		Name: TAKUMI ASANUMA	
December 28	, 2010	Takashi Ita	
Date		Name: TAKASHI ITO	